

7th IEEE Electron Devices Technology and Manufacturing (EDTM) Conference 2023

Seoul, Korea, March 7th – 10th, 2023 https://ewh.ieee.org/conf/edtm/2023/index.html

The 7th Electron Devices Technology and Manufacturing Conference (IEEE EDTM 2023) will be held in Seoul, the capital and largest metropolis of Korea which is home to the headquarters of global–leading local companies. IEEE EDTM 2023 is a full four–day conference to be held during March 7–10, 2023. IEEE EDTM 2023 aims to be a premier global forum for researchers and engineers from around the world coming to share new discoveries and discuss about any device/manufacturing

Whether you are seeking to enhance brand recognition, reinforce your reputation as an industry leader, or establish a new business, **IEEE EDTM 2023** sponsorship will enable you achieve your goals in this highly attended conference.

Sponsorship Information

About Sponsorship We have a range of sponsorship packages designed to suit all your needs. Each allows you to showcase your products and services where the top marketing decision-makers and influencers network. All sponsorship categories are filled on first-come, first-served basis.

How to reserve your sponsorship

- 1. Please download the Sponsorship Application form, fill out and e-mail it to the IEEE EDTM 2023 Secretariat (edtm2023@edtm2023.org).
- 2. Pay the contribution deadline: within a month from invoice issue date.
- 3. Please send the receipt to the secretariat for confirmation of full payment.
- 4. All payments should be transferred to the bank account. The detailed information will be announced soon.

Sponsorship Levels

Type A (Financial Backing)

LEVEL	VALUE *
Diamond	USD 17,000 / KRW 20,000,000
Platinum	USD 13,000 / KRW 15,000,000
Gold	USD 9,000 / KRW 10,000,000
Silver	USD 5,000 / KRW 6,000,000
Bronze	USD 2,500 / KRW 3,000,000

* A 10% VAT will be added for Korean companies that are required to issue a tax invoice.

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Changrock Song, Ph.D.(SK Hynix)

TCP Chair: Rino Choi, Ph.D.(Inha Univ. / KoNTRS)

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Secretariat:

Genicom Co., Ltd. E-mail: edtm2023@edtm2023.org

[Sponsorship Benefit Summary]

BENEFITS	Diamond	Platinum	Gold	Silver	Bronze
Number of complementary exhibition booths *A first-come-first-served basis	2 (booth)	1 (booth)	1 (booth)	_	-
Company logo on the program book	0	0	0	0	0
Advertisement of the company in the program book	1 Page	1 Page	1 Page	1 Page	1/2 Page
Company logo on official website, E-newsletter screen at session rooms	0	0	0	0	0
Company logo featured on the banner at the venue	0	0	0	0	0
Number of complementary full conference registration	6	4	2	1	_
Number of complementary tutorial & short course registration	3	2	1	1	-

Type B (In-kind Support)

* If the value of Type B is more than \$5,000, it will be provided a free registration benefit that Is equivalent to the Type A preferential condition.

LEVEL	BENEFITS	VALUE
Banquet	 Promotion speech during the banquet Logo on Program Book, Official Website, E-Newsletter, Screen at Session Room Logo featured on the banner at the venue Logo featured on the banner of the banquet 	
Souvenir	 Logo on Program Book, Official Website, E-Newsletter, Screen at Session Room Logo featured on the banner at the venue Logo featured on the banner of souvenir 	Please contact a secretariat.
Coffee Break	 Logo on Program Book, Official Website, E-Newsletter, Screen at Session Room Logo featured on the banner at the venue Put the company promotion leaflet during Coffee Break (on request) 	
Online Banner	– Logo on Official Website	USD 85 KRW 1,000,000

Cancellation Policy

- Before December 30, 2022: Full payment will be refunded.
- Before January 15, 2023: 50% of full payment will be refunded.
- After January 15, 2023: Full payment will not be refunded.
- Cancellation of sponsorship must be made in writing to the secretariat via e-mail.



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Sponsorship Application Form

Please fill out the below application form, and send it back to the secretariat.

IEEE EDTM 2023 Secretariat

[Tel: 042-472-7460 / Fax: 042-472-7459] [E-mail: edtm2023@edtm2023.org]

1. Information of the Company

Company Name		
President	Person in Charge	
Department		
Address		
Zip Code	Country	
Tel	Fax	
E-mail		- -

2. Sponsorship

Category	KRW	Apply (Check 'O')
Diamond	USD 17,000 / KRW 20,000,000	
Platinum	USD 13,000 / KRW 15,000,000	
Gold	USD 9,000 / KRW 10,000,000	
Silver	USD 5,000 / KRW 6,000,000	
Bronze	USD 2,500 / KRW 3,000,000	

3. Account Information

Account Holder	GENICOM CO., LTD 2023 IEEE EDTM
Account Number	661–910018–97105
Bank Name	KEB HANA BANK
Swift Code	KOEXKRSE
Bank Address	35, EULJI-RO, JUNG-GU, SEOUL, SOUTH KOREA
Branch	Jeonmin-Dong KEB HANA BANK

Name of Applicant :

Date :

Signature :